PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's	Revisio	Datum:	Seite:
PRINTED CIRCUIT BOARDS	01	4.11.2001	1/1

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
08	220	FR4	35	L20.35_20.105	P10_06	S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

08_220_FR4_35_L20.35_20.105_p10_06_s1

Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		B
	60µ	Prepreg	(60µ PrePreg-Type: 1080)	
	60µ	Prepreg		
Layer-2	35µ	Copper		A1
	200µ	L-FR4		A1
	100µ	Prepreg	(100 µ PrePreg-Type: 2125)	
	100µ	Prepreg		
Layer-4	105µ	Copper		A2
	200µ	L-FR4		A2
Layer-5	105µ	Copper		A2
	100µ	Prepreg		
	100µ	Prepreg		
Layer-6	105µ	Copper		A3
	200µ	L-FR4		A3
Layer-7	105µ	Copper		A3
	100µ	Prepreg		
	100µ	Prepreg		
	200µ	L-FR4		A4
Layer-9	35µ	Copper		A4
	60µ	Prepreg		
	60µ	Prepreg		
Layer-99	35µ	Copper		B

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